

## Abstract Submission

The program committee welcomes the submission of abstracts for ICPT 2012.

Prospective authors are asked to submit a two-page abstract (one page text, one page figures), written in English. Please assign your paper to the main topics listed and indicate the preference of oral or poster presentation. All papers have to be submitted through the ICPT 2012 website ([www.icpt2012.com](http://www.icpt2012.com)). The deadline for submission is ~~May 4, 2012~~, May 15, 2012.

## Key Dates

<del>May 4</del> May 15	Deadline for Abstracts
July 1	Acceptance Notification
September 3	Full Paper Submission

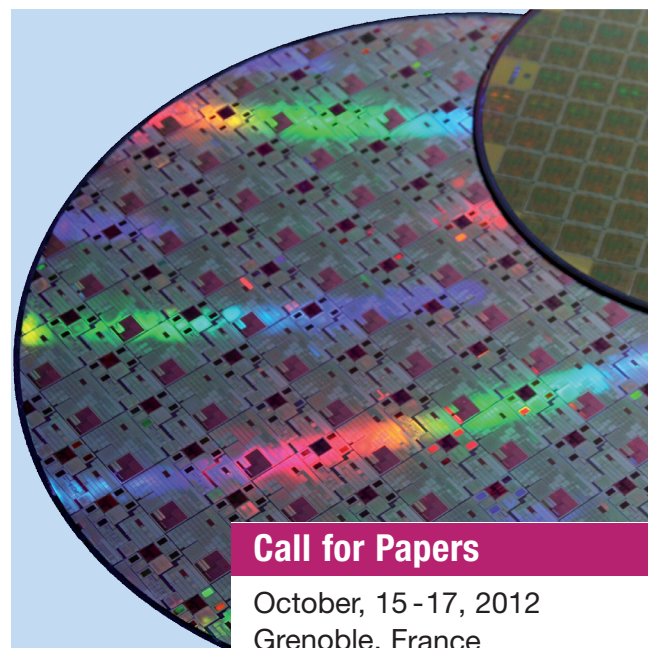
## Organizer

VDE/VDI-Society Microelectronics,  
Microsystems and Precision Engineering (GMM)  
Stresemannallee 15  
60596 Frankfurt/Main, Germany  
Phone: +49-69-6308 227  
Fax: +49-69-6308 9828  
E-Mail: [gmm@vde.com](mailto:gmm@vde.com)

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# ICPT 2012

## International Conference on Planarization/CMP Technology



### Call for Papers

October, 15 -17, 2012  
Grenoble, France

[www.icpt2012.com](http://www.icpt2012.com)

**> Extended Deadline: May 15 <**



**GMM**

VDE/VDI-SOCIETY  
MICROELECTRONICS, MICROSYSTEMS  
AND PRECISION ENGINEERING

## Invitation

Dear colleagues,

ICPT 2012 will be held at the Minatec conference center in Grenoble, France during October 15 – 17. Minatec is located in close neighborhood to CEA-Leti, the renowned French microelectronics R&D center.

The scope of the conference is to bring together colleagues from the equipment and materials manufacturers, the semiconductor industry and the research and university institutes with CMP experts from all over the world for the exchange of information of state-of-the-art research in CMP technology. ICPT 2012 provides a forum for sharing latest results, for discussing new ideas or daily problems, and, last but not least, to meet new colleagues and long-time friends.

We are looking forward to many exciting, interesting papers and to meet you in fall in the beautiful city of Grenoble.

*Gerfried Zwicker*  
(Conference Chair)

*Maurice Rivoire*  
(Program Chair)

## Main Topics

The conference will be held in English and covers any aspects of planarization and CMP technology. We are encouraging authors to submit papers, which comprise the following topics or areas of interest:

- › ILD/STI CMP
- › Cu/low-k CMP
- › CMP equipment and metrology
- › CMP process integration and control
- › Post CMP cleaning and defects
- › CMP consumables
- › CMP consumables metrology
- › CMP fundamentals (and defects)
- › Emerging technologies in CMP
- › 3D ICs/TSV applications
- › Green CMP
- › New CMP applications (data storage, LED, glass, PCB, display)